CLAIM(S):

1. A polishing pad comprising:
   (a) a polishing layer having a polishing surface, wherein the polishing surface comprises:
      (1) a plurality of grooves disposed into the polishing layer a measurable depth from the polishing surface, and
      (2) a barrier region free of grooves, and
   (c) a transparent window disposed in and surrounded by the barrier region.

2. The polishing pad of claim 1, wherein the depth transitions from a maximum value to zero proximate to the barrier region.

3. The polishing pad of claim 2, wherein the depth transition is gradual.

4. The polishing pad of claim 3, wherein the polishing pad is circular and the grooves are concentric.

5. The polishing pad of claim 4, wherein one or more of the concentric grooves are discontinuous and have a first end and a second end, and wherein the barrier region is disposed between the first and second ends.

6. The polishing pad of claim 1, wherein any one or more of the following applies,
   (a) the transparent window has an upper most window surface substantially co-planar with the polishing surface;
   (b) the polishing layer comprises polyurethane;
   (c) the transparent window comprises thermoplastic polyurethane;
   (d) the polishing pad further comprises a sub-layer.

7. A method of polishing a substrate comprising
   (i) providing a workpiece to be polished,
   (ii) contacting the workpiece with the polishing pad of claim 1, and
   (iii) abrading at least a portion of the surface of the workpiece with the polishing pad to polish the workpiece.

8. The method of claim 7, wherein the method further comprises detecting *in situ* a polishing endpoint.

9. The method of claim 7, wherein the workpiece is contacted with a chemical-mechanical polishing composition located between the workpiece and the polishing pad.

10. The method of claim 7, wherein the depth transitions from a maximum value to zero proximate to the barrier region.

11. The method of claim 10, wherein the depth transition is gradual.

12. The method of claim 11, wherein the polishing pad is circular and the grooves are concentric.

13. The method of claim 12, wherein one or more of the concentric grooves are discontinuous and have a first end and a second end, and wherein the barrier region is disposed between the first and second ends.

14. The method of claim 7, wherein any one or more of the following applies,

(a) the transparent window has an upper most window surface substantially co-planar with the polishing surface;
(b) the polishing layer comprises polyurethane;
(c) the transparent window comprises thermoplastic polyurethane;
(d) the polishing pad further comprises a sublayer.

CLAIM(S):

1. A polishing pad comprising:

(a) a polishing layer having a polishing surface, wherein the polishing surface comprises:

(1) a plurality of grooves disposed into the polishing layer a measurable depth from the polishing surface, and

(2) a barrier region free of grooves, and

(b) a transparent window disposed in and surrounded by the barrier region, wherein some or all of the grooves are concentric and one or more of the concentric grooves are discontinuous and have a first end and a second end, and wherein the barrier region is disposed between the first and second ends, and wherein the transparent window has an upper most window surface substantially co-planar with the polishing surface.

2. The polishing pad of claim 1, wherein the depth transitions from a maximum value to zero proximate to the barrier region.

3. The polishing pad of claim 2, wherein the depth transition is gradual.

4. The polishing pad of claim 3, wherein the polishing pad is circular.

5. The polishing pad of claim 1, wherein any one or more of the following applies,

b) the polishing layer comprises polyurethane;

c) the transparent window comprises thermoplastic polyurethane; and

d) the polishing pad further comprises a sub-layer.

6. A method of polishing a substrate comprising

(i) providing a workpiece to be polished,

(ii) contacting the workpiece with the polishing pad of claim 1, and

(iii) abrading at least a portion of the surface of the workpiece with the polishing pad to polish the workpiece.

7. The method of claim 6, wherein the method further comprises detecting *in situ* a polishing endpoint.

8. The method of claim 6, wherein the workpiece is contacted with a chemical-mechanical polishing composition located between the workpiece and the polishing pad.

9. The method of claim 6, wherein the depth transitions from a maximum value to zero proximate to the barrier region.

10. The method of claim 9, wherein the depth transition is gradual.

11. The method of claim 10, wherein the polishing pad is circular.

12. The method of claim 6, wherein any one or more of the following applies,

b) the polishing layer comprises polyurethane;

c) the transparent window comprises thermoplastic polyurethane; and

d) the polishing pad further comprises a sub-layer.